

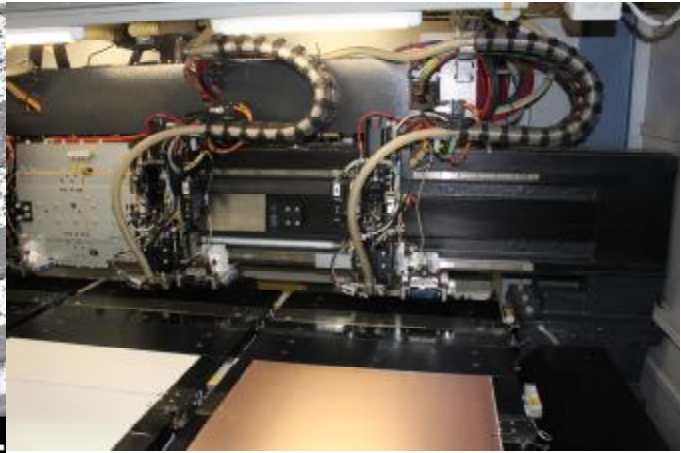


Introducing Controlled Depth Double Blind, Buried Via Complex and Hybrid Multi-Layer PCBs

Candor Industries Inc has completed testing for controlled depth drilling, resulting in accurately placed via's for complex and hybrid multilayer PCBs.



True Landless Via with Simplified Processing

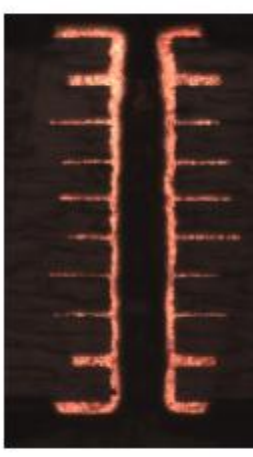


8 x 160K-rpm Controlled Depth Driller

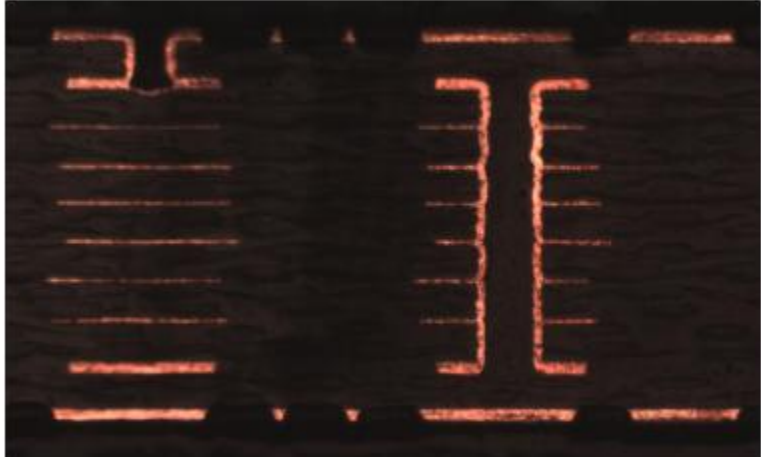
Micro-section High Tg 10-Layer Double Blind Via with 8-Layer Buried Via Technology



Blind Layer 9-10



Via Layer 1-10



Blind Layer 1-2

Buried Via Lyr 2-9

0.004 min ID	Landless Via,	Controlled depth to any layer,
10:1 aspect ratio's,	Filled or non-filled,	Pad-on-via optional,
Copper-Copper Interface	No Cap Lamination Required	Registration Enhanced

“Doing for You What Others Will Not”
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